

The Leading International Components, Packaging, and Manufacturing Technology Symposium



## IEEE CPMT Symposium Japan 2017

November 20 – 22, 2017,

Kyoto Univ. Clock Tower Centennial Hall, Kyoto, JAPAN

<http://www.ieee-csj.org/>

### “Integrated Package all around your life”

**Extended Deadline for Abstract Submissions: June 17, 2017**

“IEEE CPMT Symposium Japan (ICSJ)” is a widely-recognized international conference of the **IEEE CPMT Society**, and held annually in Kyoto in November. ICSJ will provide a platform for you to communicate and interact with global leaders in packaging technology.

**Integrated Package all around your life:** The conference started in 1992 as “The VLSI Packaging Workshop in Japan” and was re-named to “ICSJ” in 2010 and will focus on a variety of packaging technologies. Internet of Things (IoT) will make revolutionary changes to the packaging technologies for smarter usage of the devices in various application fields such as healthcare, Industry 4.0, automotive, and so on. The IoT will be supported by “Integrated Package” which is composed various types of devices (sensors, RFIDs, MEMS, wireless components, etc.). Integrated Package is one of the key technologies and exists all around your life. In 2017, the conference will emphasize three main topics: **Fan-Out technologies, Optoelectronics** and **Heterogeneous Integration Roadmap**. Additional topics of primary interest to the participants are listed below.

#### Other topics include (but not limited to):

- + 3D Packaging & Chip on Chip
- + Advanced Fine Pitch Packaging, Micro Bumping, Wafer Level CSP
- + Board-Level Integration & Integrated Substrate
- + Laminated Materials & Processing, Materials for Packaging
- + Thermal Management
- + Packaging for High-Speed Electrical Interconnect
- + Signal Integrity / Power Integrity
- + RF Components & Modules
- + Packaging for Bio-Healthcare & Wearable
- + Packaging for Automotive & Power Electronics



Bring your latest research results, share them with experts from industry and academia, and discuss your work with them. Anybody in the field of the packaging technologies is very welcome to present their latest accomplishments and participate in the discussion. The conference will provide a perfect opportunity to communicate, interact, and exchange technical idea. Young researchers within 2 years' experience in their professions and all students including Ph.D. are also welcome to the newly planned poster session called “Early Career Researcher's (ECR) session” for their start-up to the technical presentation and fruitful communication with experts. Authors are invited to submit an abstract through our web site, <http://www.ieee-csj.org>. Due to continuing interest in the symposium **we are extending the submission deadline to June 17, 2017**. Acceptance notifications will be sent by July 7, 2017. Accepted authors are

requested to submit the manuscript by September 8, 2017 for the Technical Digest, which will be available via **IEEE Xplore**. 4-page manuscript is required for the regular session, while 2-page manuscript is enough for ECR session.

## Plenary & Special Speakers

### Plenary Speakers

Jan Vardaman (TechSearch International Inc.)  
 Peter O'Brien (Tyndall National Institute)  
 Stephen E. Ralph (Georgia Institute of Technology)

### CPMT Special Speakers

William Chen (ASE Global)  
 Bill Bottoms (Advanced Polymer Monitoring Technologies)  
 S.W. Ricky Lee (Hong Kong University of Science & Technology)

### Special Speakers

Amy P. Lujan (SavanSys Solutions LLC)  
 Shuzo Akejima (Toshiba Corporation)

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### Sponsor:

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### Location:

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